

CY7C185

# 8K x 8 Static RAM

#### **Features**

- High speed
  - -15 ns
- Fast t<sub>DOE</sub>
- · Low active power
  - -715 mW
- Low standby power
  - -220 mW
- · CMOS for optimum speed/power
- Easy memory expansion with CE<sub>1</sub>, CE<sub>2</sub> and OE features
- TTL-compatible inputs and outputs
- · Automatic power-down when deselected

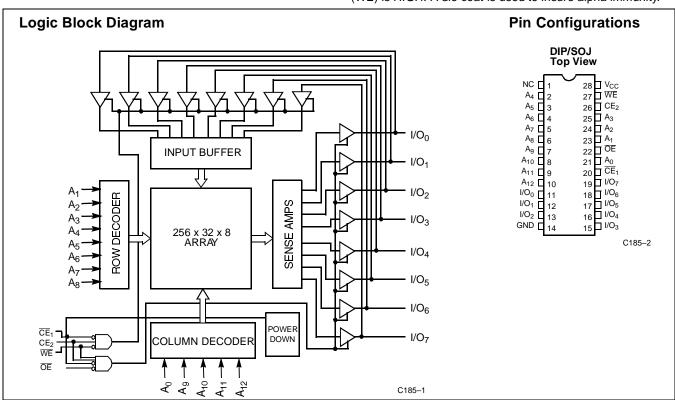
#### **Functional Description**

The CY7C185 is a high-performance CMOS static RAM organized as 8192 words by 8 bits. Easy memory expansion is

provided by an active LOW chip enable  $(\overline{CE}_1)$ , an active HIGH chip enable  $(CE_2)$ , and active LOW output enable  $(\overline{OE})$  and three-state drivers. This device has an automatic power-down feature  $(\overline{CE}_1$  or  $CE_2)$ , reducing the power consumption by 70% when deselected. The CY7C185 is in a standard 300-mil-wide DIP and SOJ package.

An active LOW write enable signal ( $\overline{\text{WE}}$ ) controls the writing/reading operation of the memory. When  $\overline{\text{CE}}_1$  and  $\overline{\text{WE}}$  inputs are both LOW and  $\text{CE}_2$  is HIGH, data on the eight data input/output pins (I/O $_0$  through I/O $_7$ ) is written into the memory location addressed by the address present on the address pins (A $_0$  through A $_1$ 2). Reading the device is accomplished by selecting the device and enabling the outputs,  $\overline{\text{CE}}_1$  and  $\overline{\text{OE}}$  active LOW,  $\text{CE}_2$  active HIGH, while  $\overline{\text{WE}}$  remains inactive or HIGH. Under these conditions, the contents of the location addressed by the information on address pins are present on the eight data input/output pins.

The input/output pins remain in a high-impedance state unless the chip is selected, outputs are enabled, and write enable  $(\overline{\text{WE}})$  is HIGH. A die coat is used to insure alpha immunity.



#### Selection Guide[1]

	7C185-12	7C185-15	7C185-20	7C185-25	7C185-35
Maximum Access Time (ns)	12	15	20	25	35
Maximum Operating Current (mA)	140	130	110	100	100
Maximum Standby Current (mA)	40/15	40/15	20/15	20/15	20/15

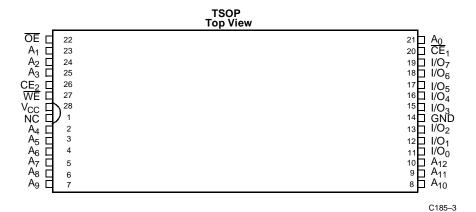
Shaded areas contain preliminary information.

Note:

1. For military specifications, see the CY7C185A/CY7C186A datasheet.



## Pin Configurations (continued)



**Maximum Ratings** 

Storage Temperature .....-65°C to +150°C

Ambient Temperature with

Power Applied.....-55°C to +125°C

Supply Voltage to Ground Potential ..... -0.5V to +7.0V

DC Voltage Applied to Outputs

in High Z State<sup>[2]</sup>......–0.5V to +7.0V

DC Input Voltage<sup>[2]</sup>.....-0.5V to +7.0V

## **Operating Range**

Range	Ambient Temperature	V <sub>CC</sub>
Commercial	0°C to +70°C	5V ± 10%

#### **Electrical Characteristics** Over the Operating Range

			7C18	35–12	7C185–15		
Parameter	Description	Test Conditions	Min.	Max.	Min.	Max.	Unit
V <sub>OH</sub>	Output HIGH Voltage	$V_{CC} = Min., I_{OH} = -4.0 \text{ mA}$	2.4		2.4		V
V <sub>OL</sub>	Output LOW Voltage	V <sub>CC</sub> = Min., I <sub>OL</sub> = 8.0 mA		0.4		0.4	V
V <sub>IH</sub>	Input HIGH Voltage		2.2	V <sub>CC</sub>	2.2	V <sub>CC</sub>	V
V <sub>IL</sub>	Input LOW Voltage[2]		-0.5	0.8	-0.5	0.8	V
I <sub>IX</sub>	Input Load Current	$GND \le V_I \le V_{CC}$	-5	+5	-5	+5	μΑ
I <sub>OZ</sub>	Output Leakage Current	$\begin{aligned} &\text{GND} \leq \text{V}_{I} \leq \text{V}_{CC}, \\ &\text{Output Disabled} \end{aligned}$	-5	+5	-5	+5	μΑ
I <sub>OS</sub>	Output Short Circuit Current <sup>[3]</sup>	V <sub>CC</sub> = Max., V <sub>OUT</sub> = GND		-300		-300	mA
I <sub>CC</sub>	V <sub>CC</sub> Operating Supply Current	V <sub>CC</sub> = Max., I <sub>OUT</sub> = 0 mA		140		130	mA
I <sub>SB1</sub>	Automatic Power-Down Current	$\begin{array}{l} \text{Max. V}_{CC}, \overline{CE}_1 \geq V_{IH} \text{ or } CE_2 \leq V_{IL} \\ \text{Min. Duty Cycle=} 100\% \end{array}$	40		40	mA	
I <sub>SB2</sub>	Automatic Power-Down Current	$\begin{aligned} &\text{Max. V}_{\text{CC}}, \ \overline{\text{CE}}_1 \geq \text{V}_{\text{CC}} - 0.3\text{V}, \\ &\text{or CE}_2 \leq 0.3\text{V} \\ &\text{V}_{\text{IN}} \geq \text{V}_{\text{CC}} - 0.3\text{V} \text{ or V}_{\text{IN}} \leq 0.3\text{V} \end{aligned}$	15		15	mA	

Shaded areas contain preliminary information.

#### Notes:

2. Minimum voltage is equal to –3.0V for pulse durations less than 30 ns.

<sup>3. -</sup>Not more than 1 output should be shorted at one time. Duration of the short circuit should not exceed 30 seconds.



# **Electrical Characteristics** Over the Operating Range (continued)

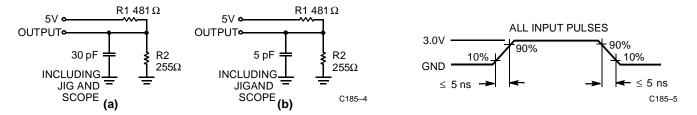
			7C18	35–20	7C185-25, 35		
Parameter	Description	Test Conditions	Min.	Max.	Min.	Max.	Unit
V <sub>OH</sub>	Output HIGH Voltage	$V_{CC} = Min., I_{OH} = -4.0 \text{ mA}$	2.4		2.4		V
V <sub>OL</sub>	Output LOW Voltage	V <sub>CC</sub> = Min., I <sub>OL</sub> = 8.0 mA		0.4		0.4	V
V <sub>IH</sub>	Input HIGH Voltage		2.2	V <sub>CC</sub>	2.2	V <sub>CC</sub>	V
V <sub>IL</sub>	Input LOW Voltage <sup>[2]</sup>		-0.5	0.8	-0.5	0.8	V
I <sub>IX</sub>	Input Load Current	$GND \le V_I \le V_{CC}$	-5	+5	-5	+5	μΑ
I <sub>OZ</sub>	Output Leakage Current	$\begin{aligned} &\text{GND} \leq \text{V}_{\text{I}} \leq \text{V}_{\text{CC}}, \\ &\text{Output Disabled} \end{aligned}$	-5	+5	<b>-</b> 5	+5	μА
I <sub>OS</sub>	Output Short Circuit Current <sup>[3]</sup>	V <sub>CC</sub> = Max., V <sub>OUT</sub> = GND		-300		-300	mA
I <sub>CC</sub>	V <sub>CC</sub> Operating Supply Current	V <sub>CC</sub> = Max., I <sub>OUT</sub> = 0 mA		110		100	mA
I <sub>SB1</sub>	Automatic Power-Down Current	$\begin{array}{l} \text{Max. V}_{CC}, \overline{CE}_1 \geq \text{V}_{\text{IH or }} CE_2 \leq \text{V}_{\text{IL}} \\ \text{Min. Duty Cycle=} 100\% \end{array}$		20		20	mA
I <sub>SB2</sub>	Automatic Power-Down Current	$\begin{array}{l} \text{Max. V}_{\text{CC}}, \overline{\text{CE}}_1 \geq \text{V}_{\text{CC}} - 0.3\text{V} \\ \text{or CE}_2 \leq 0.3\text{V} \\ \text{V}_{\text{IN}} \geq \text{V}_{\text{CC}} - 0.3\text{V or V}_{\text{IN}} \leq 0.3\text{V} \end{array}$		15		15	mA

# Capacitance<sup>[4]</sup>

Parameter	Description	Test Conditions	Max.	Unit
C <sub>IN</sub>	Input Capacitance	$T_A = 25^{\circ}C, f = 1 \text{ MHz},$	7	pF
C <sub>OUT</sub>	Output Capacitance	$V_{CC} = 5.0V$	7	pF

#### Note:

#### **AC Test Loads and Waveforms**



Equivalent to: THÉVENIN EQUIVALENT

OUTPUT• 167Ω 1.73V

<sup>4.</sup> Tested initially and after any design or process changes that may affect these parameters.



## Switching Characteristics Over the Operating Range<sup>[5]</sup>

		7C185-12		7C185-15		7C185-20		7C185-25		7C185-35		
Parameter	Description	Min.	Max.	Unit								
READ CYC	LE			1	ı			ı				
t <sub>RC</sub>	Read Cycle Time	12		15		20		25		35		ns
t <sub>AA</sub>	Address to Data Valid		12		15		20		25		35	ns
t <sub>OHA</sub>	Data Hold from Address Change	3		3		5		5		5		ns
t <sub>ACE1</sub>	CE₁ LOW to Data Valid		12		15		20		25		35	ns
t <sub>ACE2</sub>	CE <sub>2</sub> HIGH to Data Valid		12		15		20		25		35	ns
t <sub>DOE</sub>	OE LOW to Data Valid		6		8		9		12		15	ns
t <sub>LZOE</sub>	OE LOW to Low Z	2		3		3		3		3		ns
t <sub>HZOE</sub>	OE HIGH to High Z <sup>[6]</sup>		6		7		8		10		10	ns
t <sub>LZCE1</sub>	CE <sub>1</sub> LOW to Low Z <sup>[7]</sup>	3		3		5		5		5		ns
t <sub>LZCE2</sub>	CE <sub>2</sub> HIGH to Low Z	3		3		3		3		3		ns
t <sub>HZCE</sub>	CE <sub>1</sub> HIGH to High Z <sup>[6, 7]</sup> CE <sub>2</sub> LOW to High Z		6		7		8		10		10	ns
t <sub>PU</sub>	CE <sub>1</sub> LOW to Power-Up CE <sub>2</sub> to HIGH to Power-Up	0		0		0		0		0		ns
t <sub>PD</sub>	CE <sub>1</sub> HIGH to Power-Down CE <sub>2</sub> LOW to Power-Down		12		15		20		20		20	ns
WRITE CYC	LE <sup>[8]</sup>			1	ı	ı		ı		1		
t <sub>WC</sub>	Write Cycle Time	12		15		20		25		35		ns
t <sub>SCE1</sub>	CE₁ LOW to Write End	8		12		15		20		20		ns
t <sub>SCE2</sub>	CE <sub>2</sub> HIGH to Write End	8		12		15		20		20		ns
t <sub>AW</sub>	Address Set-Up to Write End	9		12		15		20		25		ns
t <sub>HA</sub>	Address Hold from Write End	0		0		0		0		0		ns
t <sub>SA</sub>	Address Set-Up to Write Start	0		0		0		0		0		ns
t <sub>PWE</sub>	WE Pulse Width	8		12		15		15		20		ns
t <sub>SD</sub>	Data Set-Up to Write End	6		8		10		10		12		ns
t <sub>HD</sub>	Data Hold from Write End	0		0		0		0		0		ns
t <sub>HZWE</sub>	WE LOW to High Z <sup>[6]</sup>		6		7		7		7		8	ns
t <sub>LZWE</sub>	WE HIGH to Low Z	3		3		5		5		5		ns

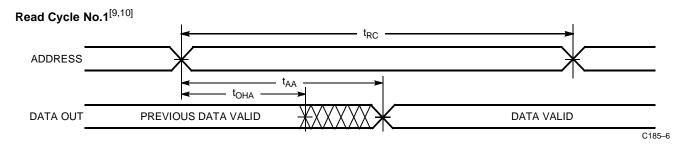
Shaded areas contain preliminary information.

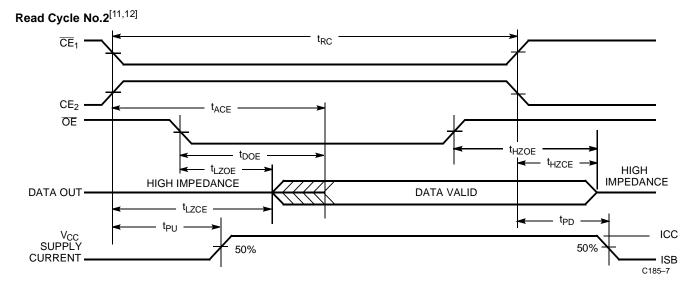
#### Notes:

Test conditions assume signal transition time of 5 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified  $I_{OL}/I_{OH}$  and 30-pF load capacitance.  $I_{HZCE}$ , and  $I_{HZCE}$ , and  $I_{HZCE}$  are specified with  $C_L = 5$  pF as in part (b) of AC Test Loads. Transition is measured  $\pm 500$  mV from steady state voltage. At any given temperature and voltage condition,  $I_{HZCE}$  is less than  $I_{LZCE}$  for any given device. The internal write time of the memory is defined by the overlap of  $CE_1$  LOW,  $CE_2$  HIGH, and WE LOW. All 3 signals must be active to initiate a write and either signal can terminate a write by going HIGH. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write.

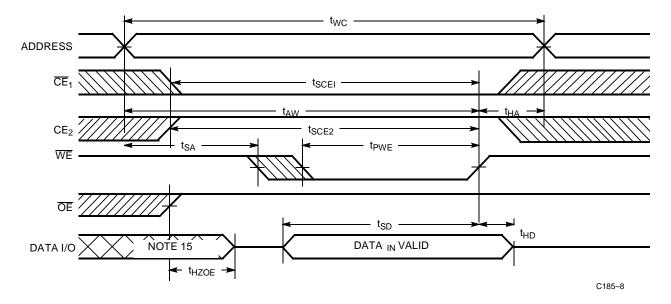


# **Switching Waveforms**





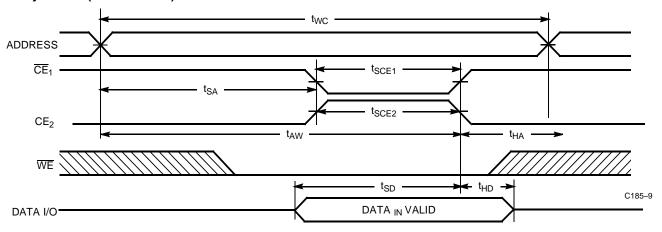
# Write CycleNo.1 ( $\overline{\text{WE}}$ Controlled) $^{[10,12]}$



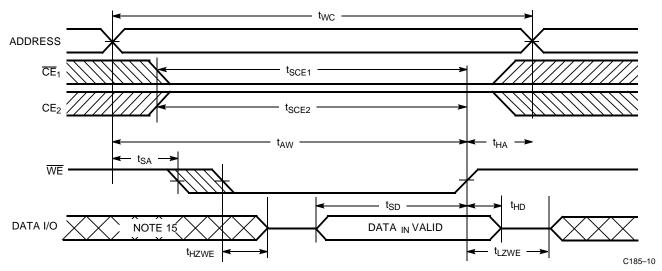


## Switching Waveforms (continued)

## Write Cycle no.2 (CE Controlled)[12,13,15]



# Write Cycle No.3 (WE Controlled, OE LOW)[12,13,14,15]



#### Notes:

- Device is continuously selected.  $\overline{OE}$ ,  $\overline{CE}_1 = V_{IL}$ .  $CE_2 = V_{IH}$ .  $\overline{WE}$  is HIGH for read cycle.

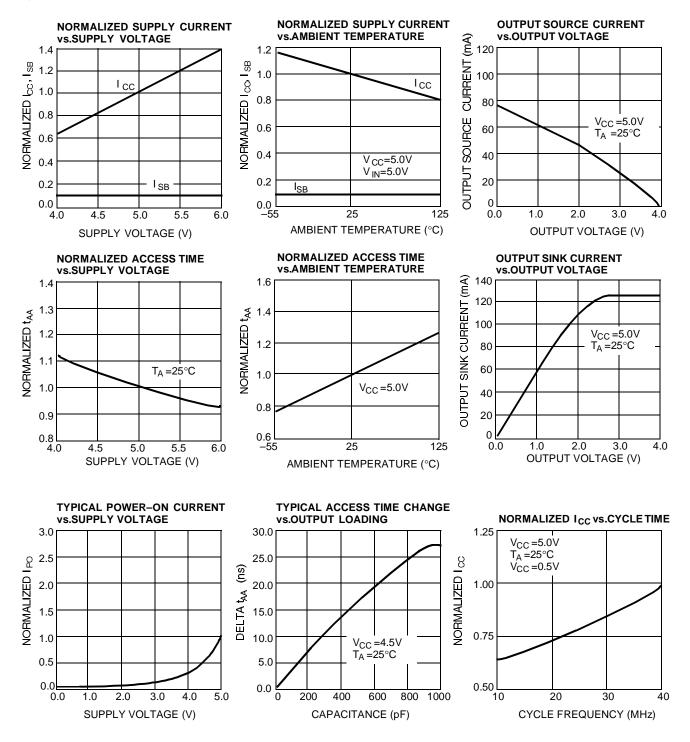
  Data I/O is High Z if  $\overline{OE} = V_{IH}$ ,  $\overline{WE} = V_{IL}$  or  $CE_2 = V_{IL}$ .

  The internal write time of the memory is defined by the overlap of  $\overline{CE}_1$  LOW,  $CE_2$  HIGH and  $\overline{WE}$  LOW.  $\overline{CE}_1$  and  $\overline{WE}$  must be LOW and  $CE_2$  must be HIGH to initiate write. A write can be terminated by  $\overline{CE}_1$  or  $\overline{WE}$  going HIGH or  $CE_2$  going LOW. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write.

  The minimum write cycle time for write cycle #3 ( $\overline{WE}$  controlled,  $\overline{OE}$  LOW) is the sum of  $t_{HZWE}$  and  $t_{SD}$ . If  $\overline{CE}_1$  goes HIGH or  $CE_2$  goes LOW simultaneously with  $\overline{WE}$  HIGH, the output remains in a high-impedance state. During this period, the I/Os are in the output state and input signals should not be applied.



## **Typical DC and AC Characteristics**





## **Truth Table**

CE <sub>1</sub>	CE <sub>2</sub>	WE	OE	Input/Output	Mode
Н	Χ	Χ	Χ	High Z	Deselect/Power-Down
X	L	Х	Х	High Z	Deselect/Power-Down
L	Н	Н	L	Data Out	Read
L	Н	L	Х	Data In	Write
L	Н	Н	Н	High Z	Deselect

# **Address Designators**

Address Name	Address Function	Pin Number
A4	Х3	2
A5	X4	3
A6	X5	4
A7	X6	5
A8	X7	6
A9	Y1	7
A10	Y4	8
A11	Y3	9
A12	Y0	10
A0	Y2	21
A1	X0	23
A2	X1	24
A3	X2	25

## **Ordering Information**

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
12	CY7C185-12PC	P21	28-Lead (300-Mil) Molded DIP	Commercial
	CY7C185-12VC	V21	28-Lead Molded SOJ	
15	CY7C185-15PC	P21	28-Lead (300-Mil) Molded DIP	Commercial
	CY7C185-15VC	V21	28-Lead Molded SOJ	
	CY7C185-15ZC	Z28	28-Lead Thin Small Outline Package	
20	CY7C185-20PC	P21	28-Lead (300-Mil) Molded DIP	Commercial
	CY7C185-20VC	V21	28-Lead Molded SOJ	
	CY7C185-20ZC	Z28	28-Lead Thin Small Outline Package	
25	CY7C185-25PC	P21	28-Lead (300-Mil) Molded DIP	Commercial
	CY7C185-25VC	V21	28-Lead Molded SOJ	
	CY7C185-25ZC	Z28	28-Lead Thin Small Outline Package	
35	CY7C185-35PC	P21	28-Lead (300-Mil) Molded DIP	Commercial
	CY7C185-35VC	V21	28-Lead Molded SOJ	
	CY7C185-35ZC	Z28	28-Lead Thin Small Outline Package	

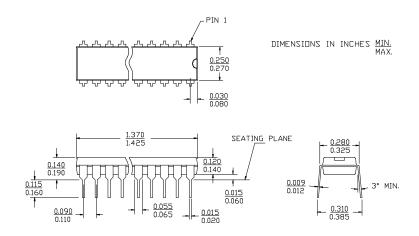
Shaded areas contain preliminary information.

Document #: 38-00037-K

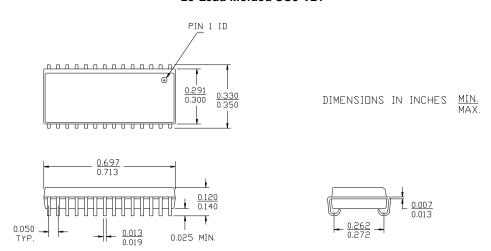


## **Package Diagrams**

### 28-Lead (300-Mil) Molded DIP P21



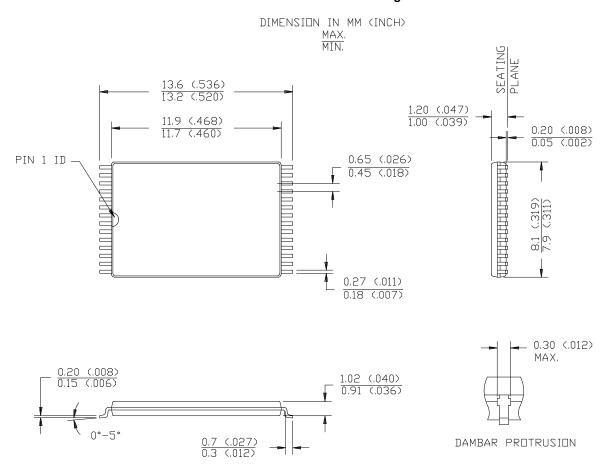
### 28-Lead Molded SOJ V21





### Package Diagrams (continued)

### 28-Lead Thin Small outline Package Z28



<sup>©</sup> Cypress Semiconductor Corporation, 1996. The information contained herein is subject to change without notice. Cypress Semiconductor Corporation assumes no responsibility for the use of any circuitry other than circuitry embodied in a Cypress Semiconductor product. Nor does it convey or imply any license under patent or other rights. Cypress Semiconductor does not authorize its products for use as critical components in life-support systems where a malfurnion or failure may reasonably be expected to result in significant injury to the user. The inclusion of Cypress Semiconductor products in life-support systems application implies that the manufacturer assumes all risk of such use and in doing so indemnifies Cypress Semiconductor against all charges.